

Linmei Yang

List of Publications by Year in descending order

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#	ARTICLE	IF	CITATIONS
1	Upconversion luminescence, intensity saturation effect, and thermal effect in Gd ₂ O ₃ :Er ₃ ,Yb ₃₊ nanowires. <i>Journal of Chemical Physics</i> , 2005, 123, 174710.	3.0	194
2	Three-photon upconversion luminescence phenomenon for the green levels in Er ³⁺ /Yb ³⁺ codoped cubic nanocrystalline yttria. <i>Solid State Communications</i> , 2004, 132, 409-413.	1.9	112
3	Facile synthesis of magnetic Co ₃ O ₄ /BFO nanocomposite for effective reduction of nitrophenol isomers. <i>Chemosphere</i> , 2019, 219, 914-922.	8.2	37
4	Unusual power-dependent and time-dependent upconversion luminescence in nanocrystals Y ₂ O ₃ :Ho ³⁺ /Yb ³⁺ . <i>Journal of Luminescence</i> , 2006, 116, 101-106.	3.1	28
5	Anchoring Co ₃ O ₄ on BiFeO ₃ : achieving high photocatalytic reduction in Cr(VI) and low cobalt leaching. <i>Journal of Materials Science</i> , 2019, 54, 12424-12436.	3.7	28
6	Growth Behavior of Intermetallic Compounds in Cu/Sn _{3.0} Ag _{0.5} Cu Solder Joints with Different Rates of Cooling. <i>Journal of Electronic Materials</i> , 2015, 44, 590-596.	2.2	19
7	Fabrication of La-Doped Bi ₂ O ₃ Nanoparticles with Oxygen Vacancies for Improving Photocatalytic Activity. <i>Catalysis Letters</i> , 2020, 150, 640-651.	2.6	18
8	Nonlinear blue upconversion luminescence in $\text{Gd}_{2}\text{O}_{3}:\text{Er}^{3+},\text{Yb}^{3+}$. <i>Solid State Communications</i> , 2009, 149, 1814-1817.	2.6	9
9	Improvements of microstructure and hardness of lead-free solders doped with Mo nanoparticles. <i>Materials Letters</i> , 2021, 304, 130654.	2.6	9
10	Photocatalytic Activity of Bi ₂ O ₃ Enhanced by the Addition of Ce ³⁺ /Ce ⁴⁺ Synthesized by Ethylene Glycol-assisted Solvothermal Method. <i>ChemistrySelect</i> , 2020, 5, 5799-5808.	1.5	7
11	Evolution of microstructure and effects on crack formation of Sn _{3.0} Ag _{0.5} Cu/Cu solder joints under accelerated thermal cycling. <i>Materials Research Express</i> , 2019, 6, 076518.	1.6	4
12	Microstructure growth and tensile strength of Cu/Sn _{3.0} Ag _{0.5} Cu/Cu solder joints. <i>Materials Research Express</i> , 2019, 6, 016517.	1.6	1
13	Strengthening effect of molybdenum (Mo) addition in Sn-58Bi alloy during isothermal aging. <i>Materials Research Express</i> , 2019, 6, 116547.	1.6	0